

1 1. A method comprising:
2 microfabricating a vacuum sensor; and
3 enclosing said vacuum sensor with an integrated
4 circuit inside an enclosure.

1 2. The method of claim 1 including integrating said
2 vacuum sensor and said integrated circuit in the same
3 substrate.

1 3. The method of claim 1 including integrating said
2 vacuum sensor and said integrated circuit on separate dice
3 and enclosing said separate dice in the same enclosure.

1 4. The method of claim 1 including microfabricating
2 the vacuum sensor as a serpentine wire.

1 5. The method of claim 4 including microfabricating
2 the sensor as a suspended, serpentine wire.

1 6. The method of claim 4 including forming a contact
2 on a surface, said contact coupled to said wire.

1 7. The method of claim 6 including making said
2 contact U-shaped.

1 8. The method of claim 1 including providing an
2 enclosure that covers said vacuum sensor and said
3 integrated circuit and provides a hermetically sealed
4 chamber.

1 9. The method of claim 8 including providing an
2 electrical connection under said enclosure to the exterior
3 of said chamber.

1 10. An integrated circuit device comprising:
2 a microfabricated vacuum sensor;
3 an integrated circuit;
4 an enclosure; and
5 a substrate, said enclosure mounted on said
6 substrate and enclosing both said vacuum sensor and said
7 circuit within said enclosure.

1 11. The device of claim 10 wherein said vacuum sensor
2 and said integrated circuit are monolithically integrated
3 in the same die.

1 12. The device of claim 10 wherein said vacuum sensor
2 and integrated circuit are on separate dice.

1 13. The device of claim 10 wherein said vacuum sensor
2 includes a serpentine wire.

1 14. The device of claim 13 wherein said wire is
2 suspended.

1 15. The device of claim 13 including a contact
2 coupled to said wire.

1 16. The device of claim 15 wherein said contact is U-
2 shaped.

1 17. The device of claim 16 including a vertical
2 portion extending upwardly from said contact to said wire.

1 18. The device of claim 10 wherein said enclosure is
2 hermetically sealed.

1 19. The device of claim 18 including an electrical
2 connection extending under said enclosure to the exterior
3 of said enclosure.

1 20. An integrated circuit device comprising:
2 a substrate;
3 a vacuum sensor integrated in said substrate;
4 an integrated circuit integrated in said
5 substrate; and

6 an enclosure, said enclosure mounted on said
7 substrate and enclosing both said vacuum sensor and said
8 integrated circuit within said enclosure.

1 21. The device of claim 20 wherein said vacuum sensor
2 includes a serpentine wire.

1 22. The device of claim 21 wherein said wire is
2 suspended.

1 23. The device of claim 21 including a contact
2 coupled to said wire.

1 24. The device of claim 23 wherein said contact is U-
2 shaped.

1 25. The device of claim 24 including a vertical
2 portion extending upwardly from said contact to said wire.

1 26. The device of claim 20 wherein said enclosure is
2 hermetically sealed.

1 27. The device of claim 26 including an electrical
2 connection extending under said enclosure to the exterior
3 of said enclosure.